



Material Content Data Sheet



Sales Product Name		IPB160N04S3-H2		Issued		29. August 2013			
MA#		MA000363377							
Package		PG-TO263-7-3		Weight*		1526.35 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.313	0.54	0.54	5447	5447	
leadframe	non noble metal	iron	7439-89-6	0.909	0.06		596		
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179		
	non noble metal	copper	7440-50-8	907.924	59.48	59.56	594832	595607	
wire	non noble metal	aluminium	7429-90-5	11.132	0.73	0.73	7293	7293	
encapsulation	organic material	carbon black	1333-86-4	8.692	0.57		5695		
	plastics	epoxy resin	-	95.613	6.26		62641		
	inorganic material	silicondioxide	60676-86-0	475.166	31.13	37.96	311308	379644	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8069	8069	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	176	
solder	noble metal	silver	7440-22-4	0.144	0.01		94		
	non noble metal	tin	7440-31-5	0.115	0.01		75		
	non noble metal	lead	7439-92-1	5.487	0.36	0.38	3595	3764	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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